



-, \$ 1 \* 6 8& + \$ 1 \* -, 1 \* ( / ( & 7 5 2 1 , & 6 7 ( & + 1 2 / 2 \* 4 7 & 2

## SMA ) Plastic-Encapsulate Diodes

### SS22 ) THRU SS220 ) Schottky Rectifier Diodes

#### Features

- " ) \$ 9 \$
- " 9 5 5 0 9 9
- " + L J K V X U J H F X U U H Q W F D S D E L O L W \

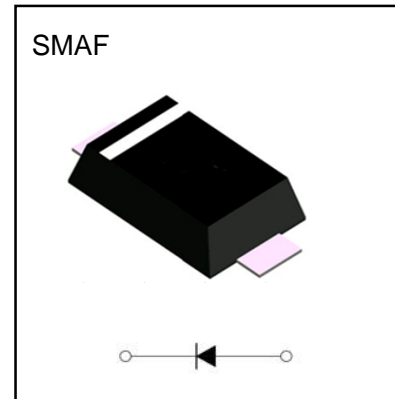
"Polarity: Color band denotes cathode

#### Applications

- " 5 H F W L I L H U

#### Marking

- " 6 6 ;
- ; : ) U R P 7 R



/ L P L W 1 0 0 X H V \$ E V R O X W H 0 D [ L P X P 5 D W L Q J

Item	Symbol	Unit	Test Conditions	SS														
				2 )	3 )	4 )	5 )	6 )	8 )	10 )	15 )	20 )						
Repetitive Peak Reverse Voltage	$V_{RRM}$	V		20	30	40	50	60	80	100	150	200						
Maximum RMS Voltage	$V_{RMS}$	V		14	21	28	35	42	56	70	105	140						
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, 7 / ) L J	.0														
Surge(Non-repetitive)Forward Current	$I_{FSM}$	A	60Hz Half-sine wave, 1 cycle, $T_a=25^{\circ}C$	0														
Junction Temperature	$T_J$			-55~+125					-55~+150									
Storage Temperature	$T_{STG}$			-55 ~ +150														

#### Electrical Characteristics (T =25 Unless otherwise specified A

Item	Symbol	Unit	Test Condition	SS														
				2 )	3 )	4 )	5 )	6 )	8 )	10 )	15 )	20 )						
Peak Forward Voltage	$V_F$	V	$I_F = .0A$	0.55		0.70		0.85		0.95								
Peak Reverse Current	$I_{RRM1}$	mA	$V_{RM}=V_{RRM}$	$T_a=25$		0.5		0										
	$I_{RRM2}$			$T_a=100$		10		5.0										
Thermal Resistance(Typical)	$R_{\theta J-A}$	/ W	Between junction and ambient	5														
	$R_{\theta J-L}$		Between junction and terminal	17														

#### Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

# Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

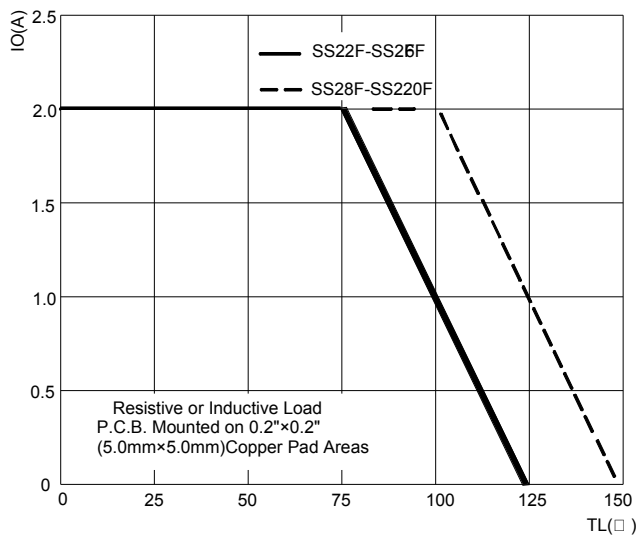


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

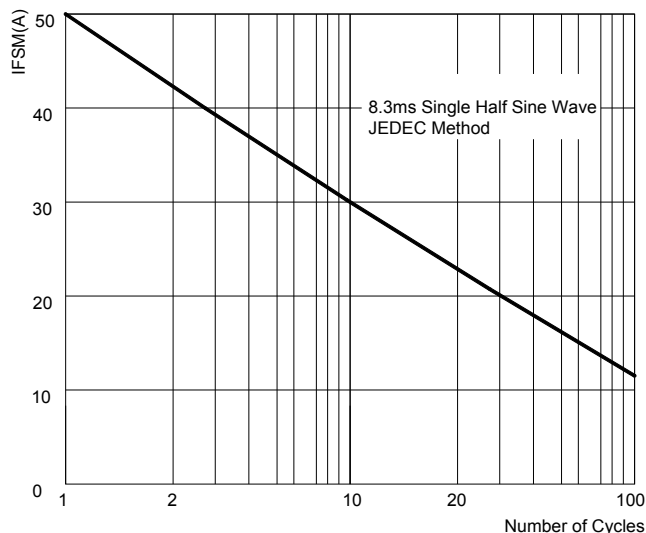


FIG.3: TYPICAL FORWARD CHARACTERISTICS

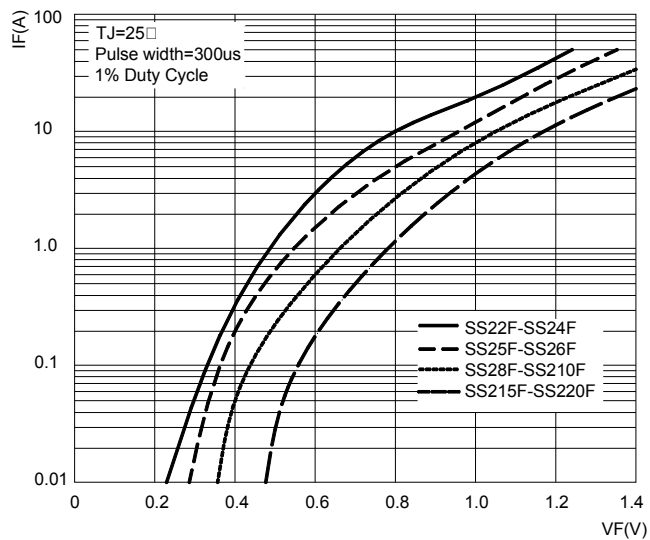
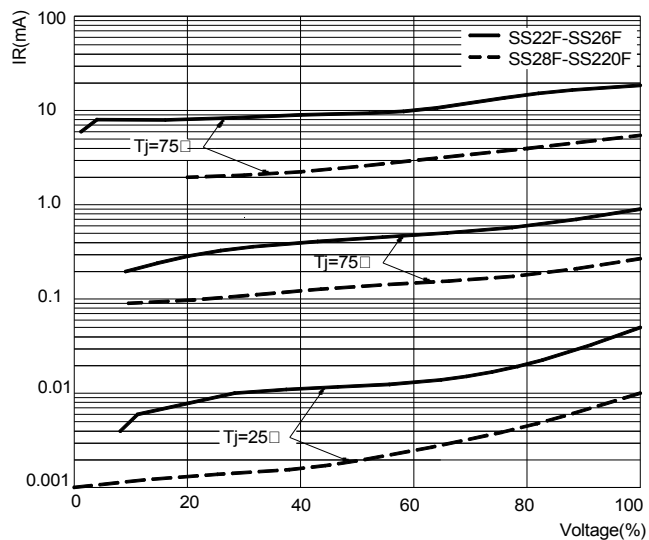
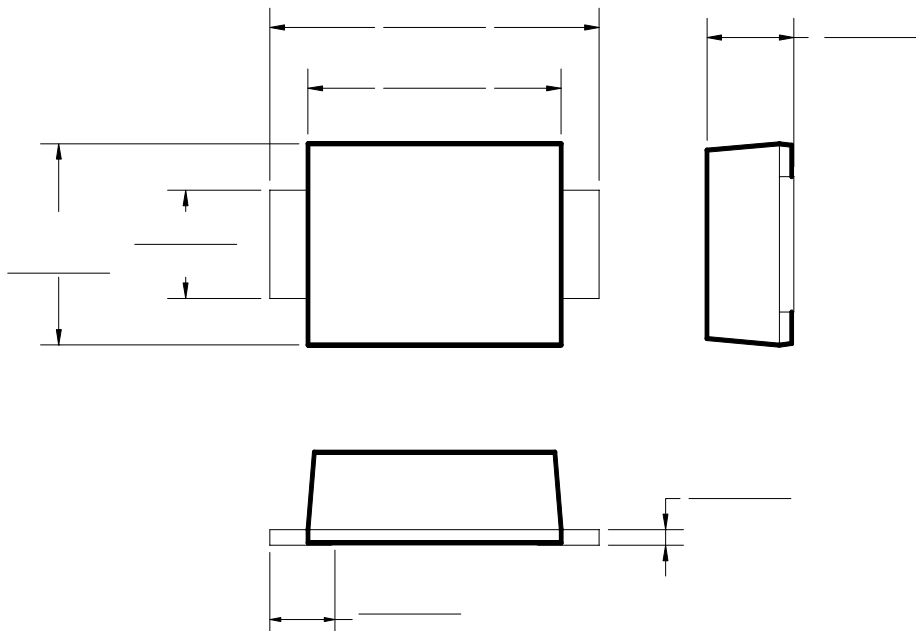


FIG.4: TYPICAL REVERSE CHARACTERISTICS

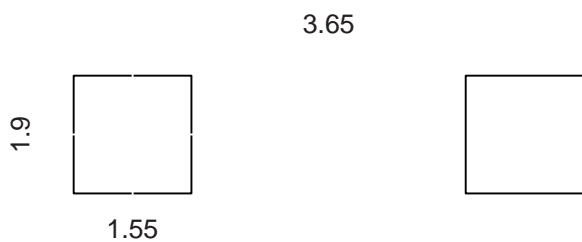


## SMAF Package Outline Dimensions



Dimensions in inches and (millimeters)

## SMAF Suggested Pad Layout



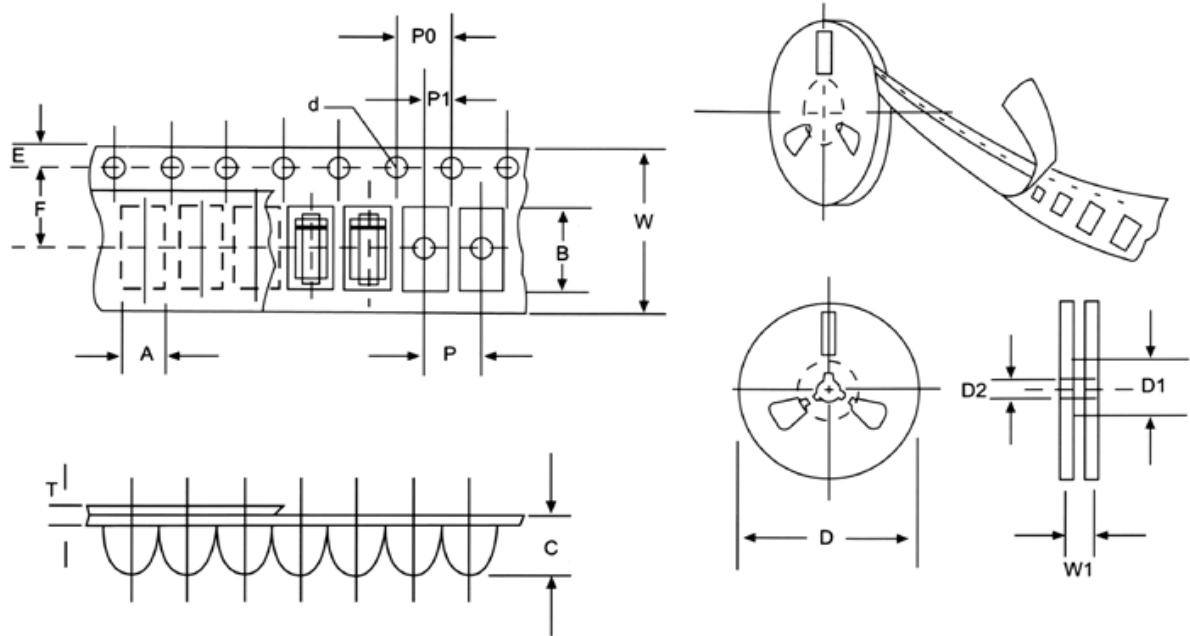
**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.

**NOTICE**

JSCJ reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. JSCJ does not assume any liability arising out of the application or use of any product described herein.

## Reel Taping Specifications For Surface Mount Devices- SMAF



**FIG: CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING**

ITEM	SYMBOL	SMAF mm(inch)
Carrier width	A	2.83+0.1(0.112+0.004)
Carrier length	B	4.90+0.1(0.193+0.004)
Carrier depth	C	1.45+0.1(0.057+0.004)
Sprocket hole	d	1.55+0.05(0.061+0.002)
Reel outside diameter	D	178+2.0(7.0+0.079)
Reel inner diameter	D1	54±1.0(2.13±0.039)
Feed hole diameter	D2	13+0.5(0.512+0.020)
Sprocket hole position	E	1.75+0.1(0.069+0.004)
Punch hole position	F	5.5+0.05(0.217+0.002)
Punch hole pitch	P	4.0+0.1(0.157+0.004)
Sprocket hole pitch	P0	4.0+0.1(0.157+0.004)
Embossment center	P1	2.0+0.1(0.079+0.004)
Total tape thickness	T	0.23-0.29(0.009-0.011)
Tape width	W	12.0+0.1(0.472+0.004)
Reel width	W1	16.8+2.0(0.661+0.079)

NOTE: Devices are packed in accordance with EIA standard RS-481-A and specification given above.